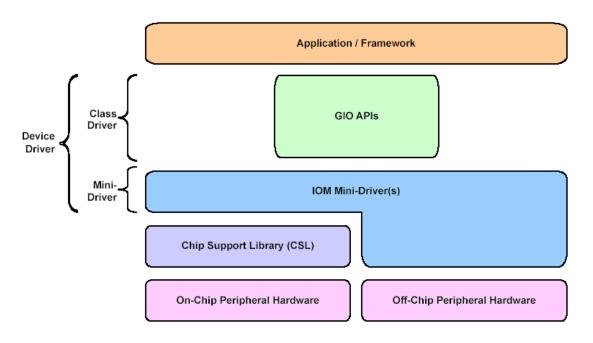


- Middle layer of the driver conforms to IO Mini driver model defined by the DSP/BIOS DDK (Device Driver Development Kit) Framework.
- Supports EDMA and interrupt modes of operation (Interrupt mode not tested)
- Supports receive and transmit in I2S mode and transmit in DIT mode



Description

Details of tools used and versions are available in release notes



Capabilities

The following table gives a quick overview of the supported API provided by the GIO layer to interact with the driver

GIO API called by application	mini-driver API called	Description			
GIO_create (name, Int mode, Int *status, Ptr chanParams, GIO_Attrs *attrs);	static Int mcasp_mdCreateChan (Ptr *chanp, Ptr devp, String name, Int mode, Ptr chanParams, IOM_TiomCallback cbFxn, Ptr cbArg);	This assigns one of the device channels to be used for the operation (rcv/xmt). It hooks up the necessary ISRs and configures the associated eDMA channel.			
GIO_Delete (GIO_Handle gioChan);	static Int mcasp_mdDeleteChan(Ptr chanp);	Frees up resources held by channel.			
GIO_submit (gioChan, IOM_READ, bufp, psize, appCallback);	static Int mcasp_mdSubmitChan(Ptr chanp, IOM_Packet *packet);	Submits a read packet to configure the McASP receive section with.			
GIO_submit (gioChan, IOM_WRITE, bufp, psize, appCallback);	static Int mcasp_mdSubmitChan(Ptr chanp, IOM_Packet *packet);	Submits a write packet to configure the McASP transmit section with.			
GIO_Flush(gioChan);	static Int mcasp_mdControlChan(Ptr chanp, Uint16 cmd, Ptr args);	Drains all existing packets for this channel. This call also prevents stalls submission of packets to the channel			
GIO_Abort(gioChan);	static Int mcasp_mdControlChan(Ptr chanp, Uint16 cmd, Ptr args);	This call aborts all packets submitted to the channel and places the corresponding state machine in reset.			
GIO_Control(gioChan, cmd, args);	static Int mcasp_mdControlChan(Ptr chanp, Uint16 cmd, Ptr args);	This submits other control commands to the mini-driver.			



Driver Performance Characteristics

Release Mode:

MCASP DEVICE DRIVER SUB-COMPONENT	PROGRAM MEMORY (IN BYTES)	DATA MEMORY (IN BYTES)		
		MEMORY TYPE		TOTAL
		INITIALIZED	UN INITIALIZED	
dda	2284	40	156	2480
ddc	24212	152	4232	28596
llc	9500	0	660	9500
Total	35996	192	4388	40576

System Components Total Memory (Code & Data): 40576 Bytes

Note: The Driver Performance Characteristics can be included once testing is done on DM648/C6452 SOC.

Driver Profiling Characteristics

SIO								
Trial-1	Trial-2	Trial-3	Average (usecs)	Maximum (usecs)	Minimum (usecs)			
2301263	2301263	2301260	2301262	2301263	2301260			
57	56	57	57	57	56			
1	1	1	1	1	1			
1	1	1	1	1	1			
20	20	20	20	20	20			
39	39	39	39	39	39			
	2301263 57 1 1 20	Trial-1 Trial-2 2301263 2301263 57 56 1 1 1 1 20 20	Trial-1 Trial-2 Trial-3 2301263 2301263 2301260 57 56 57 1 1 1 1 1 1 20 20 20	Trial-1 Trial-2 Trial-3 Average (usecs) 2301263 2301263 2301260 2301262 57 56 57 57 1 1 1 1 1 1 1 1 20 20 20 20	Trial-1 Trial-2 Trial-3 Average (usecs) Maximum (usecs) 2301263 2301263 2301260 2301262 2301263 57 56 57 57 57 1 1 1 1 1 1 1 1 1 1 20 20 20 20 20			

Note: Due to the initialization of codec related steps GIO_create - Tx is taking extremely large time.

API Profiled	Trial-1	Trial-2	Trial-3	Average (usecs)	Maximum (usecs)	Minimum (usecs)
GIO_create - Tx	2301265	2301265	2301264	2301265	2301265	2301264
GIO_create - Rx	55	55	55	55	55	55
GIO_Submit - Write	23	22	22	22	23	22
GIO_Submit- Read	14	13	13	13	14	13
GIO_Delete - Tx	20	30	29	26	30	20
GIO_Delete- Rx	38	82	84	68	84	38

Note: Due to the initialization of codec related steps

GIO_create - Tx is taking extremely large time.



Driver Performance Characteristics

AUDIO WRITE

Test Setup Information	Sampling Rate in Hz	Word Length in bits	No. of channels/sample	DMA Mode		
					Buffer	
				No. of	Size in	Duration
				bytes/Sec	Bytes	in Sec
ARM Frequency = 26 MHZ	8000	32	1	32931	15360	50
	12600	32	1	51916	15360	50
	44100	32	1	179896	15360	50
	48000	32	1	195788	15360	50
	96000	32	1	391230	15360	50

AUDIO READ

Test Setup Information	Sampling Rate in Hz	Word Length in bits	No. of channels/sample	D	MA Mode)
					Buffer	
				No. of bytes/Sec	Size in KB	Duration in Sec
ARM Frequency = 26 MHZ	8000	32	1	32931	15360	50
	12600	32	1	51609	15360	50
	44100	32	1	179180	15360	50
	48000	32	1	195779	15360	50
	96000	32	1	391249	15360	50

References

[1] DSP/BIOS Driver Developer's guide

[2] McASP Programmer's Reference Guide

Glossary

IOM TI Terminology, Input/Output Mini Driver.

DDC TI Terminology, Device Driver Core that is OS independent

CSL Chip Support Library

GIO Generic I/O Module

McASP Multi-channel Audio Serial Port I2S Inter-Integrated Sound protocol DIT Digital Audio Interface Transmission

IOM Input/Output Module

EDMA Enhanced Direct Memory Access





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